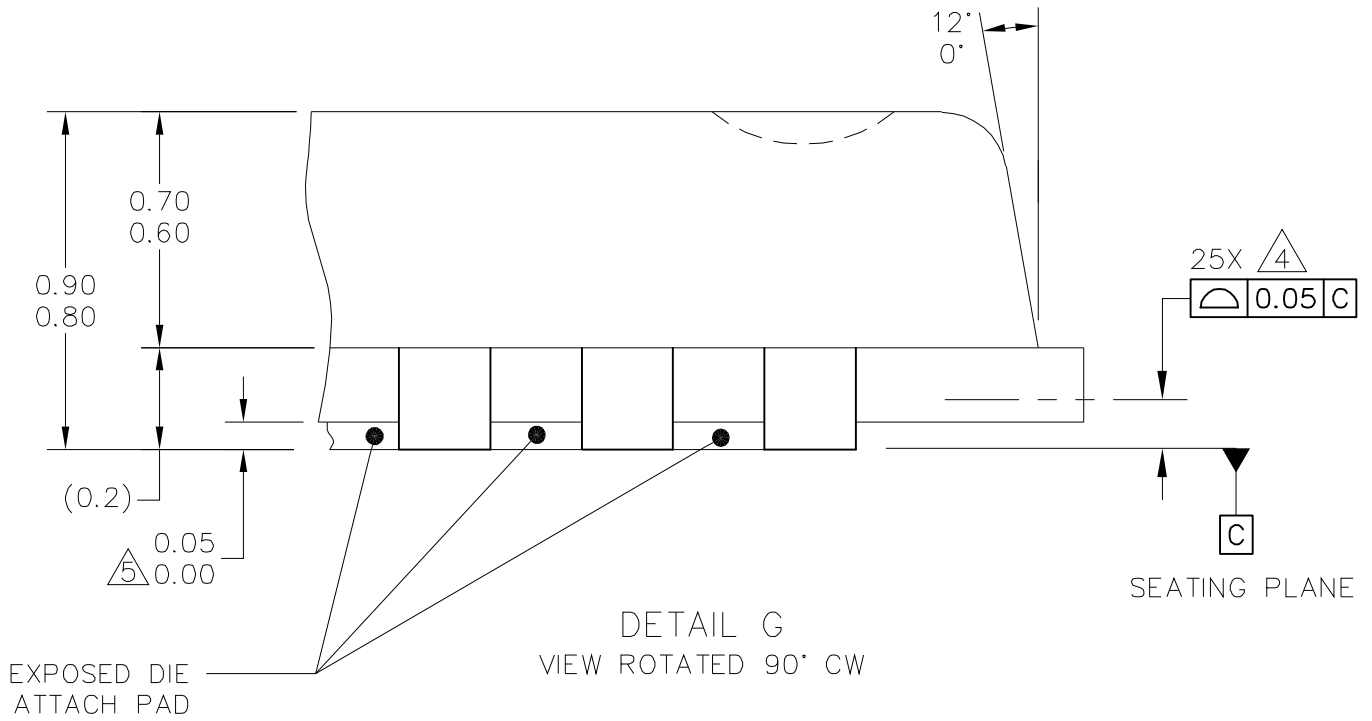


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: QFN (PUNCH), THERMALLY ENHANCED 4 X 4 X 0.85, 0.5 PITCH, 24 TERMINAL		DOCUMENT NO: 98ASA00462D	REV: A
		STANDARD: NON-JEDEC	
		SOT616-7	12 JAN 2016



© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: QFN (PUNCH), THERMALLY ENHANCED 4 X 4 X 0.85, 0.5 PITCH, 24 TERMINAL		DOCUMENT NO: 98ASA00462D	REV: A
		STANDARD: NON-JEDEC	
		SOT616-7	12 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM TERMINAL TIP.
4. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. THIS DIMENSION APPLIES ONLY FOR TERMINALS.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: QFN (PUNCH), THERMALLY ENHANCED 4 X 4 X 0.85, 0.5 PITCH, 24 TERMINAL		DOCUMENT NO: 98ASA00462D	REV: A
		STANDARD: NON-JEDEC	
		SOT616-7	12 JAN 2016